[0094]

[Table 1]

		Example 1	Example 2	Example 3	Example 4	Example 5	Comparative Example 1	Comparative Example 2	Comparative Example 3	Comparative Example 4
Blend amounts (part(s) by weight)	Epoxy resin 1	3.3	3.3	3.3	3.3	3.3	5.6	2.3	4.3	-
	Epoxy resin 2	-	-	-	-	-	-	-	-	7.5
	Phenol resin 1	3.5	3.5	3.5	3.5	3.5	5.8	2.5	4.5	-
	Phenol resin 2	-	-	-	-	-	-	-	-	3.9
	Thermoplastic resin	3.0	3.0	3.0	3.0	3.0	5.0	6.0	10.0	5.0
	Inorganic filler 1	88.0	58.0	58.0	58.0	88.0	80.0	28.0	70.0	80.0
	Inorganic filler 2	-	30.0	-	-	-	-	60.0	-	-
	Inorganic filler 3	-	-	25.0	25.0	-	-	-	-	-
	Inorganic filler 4	-	-	5.0	5.0	-	-	-	-	-
	Silane coupling agent	0.3	0.3	0.3	0.3	0.3	0.5	0.3	0.3	0.5
	Carbon black	0.3	0.3	0.3	0.3	0.3	0.5	0.3	0.3	0.5
	Flame retardant	1.5	1.5	1.5	1.5	1.5	2.4	0.5	1.5	2.4
	Curing accelerator	0.1	~~1~~0.1	0.1	0.1	0.1	0.2	0.1	0.1	0.2
Content [% by volume] of inorganic filler		80	80	80	80	80	69	80	80	69
Production method		Kneading	Kneading	Kneading	Kneading	Coating	Kneading	Kneading	Kneading	Kneading
Sheet thickness [μm]		200	200	200	200	200	200	200	200	200
Evaluation	Minimum melt viscosity [Pa·s]	6000	9500	16000	16000	5800	1800	22000	1000	1900
	Storage modulus [GPa] after curing	2.5	3.5	4	4	2.5	1.5	2.3	0.9	21
	Linear expansion coefficient [ppm/K] after curing	7	7	6	6	7	15	8	30	18
	Glass transition temperature [°C]	110	113	115	115	110	100	111	95	195
	Entry of resin into hollow region: Gap width [μm]	30	30	30	90	30	30	30	30	30
	Entry of resin into hollow region: Entry quantity [μm]	18	13	10	18	19	50	35	45	47
	Entry of resin into hollow region: Judgment	○	○	○	○	○	×	×	×	×
	Sheet warp: Warp quantity [mm]	0.5	0.5	0.7	0.7	0.5	1.8	0.8	3.9	2.6
	Sheet warp: Judgment	○	○	○	○	○	×	○	×	×

CLAIMS

1. A hollow sealing resin sheet, comprising an epoxy resin and an inorganic filler in a content of 70 to 90% by volume both inclusive, the hollow sealing resin sheet having:

a minimum melt viscosity of 2000 to 20000 Pa·s both inclusive at temperatures of 60 to 130°C according to a dynamic viscoelasticity measurement;

a storage modulus of 1 to 10~~20~~ GPa both inclusive at 20°C after the resin sheet is thermally cured at 150°C for 1 hour; and

a linear expansion coefficient of 5 to 15 ppm/K both inclusive at a glass transition temperature or lower after the resin sheet is thermally cured at 150°C for 1 hour.

2. A production method for a hollow package, comprising:

a laminating step of laminating the hollow sealing resin sheet recited in claim 1 over one or more electronic devices arranged over an adherend to cover the electronic devices while a hollow region is maintained between the adherend and the electronic devices; and

a sealed body forming step of curing the hollow sealing resin sheet to form a sealed body.